

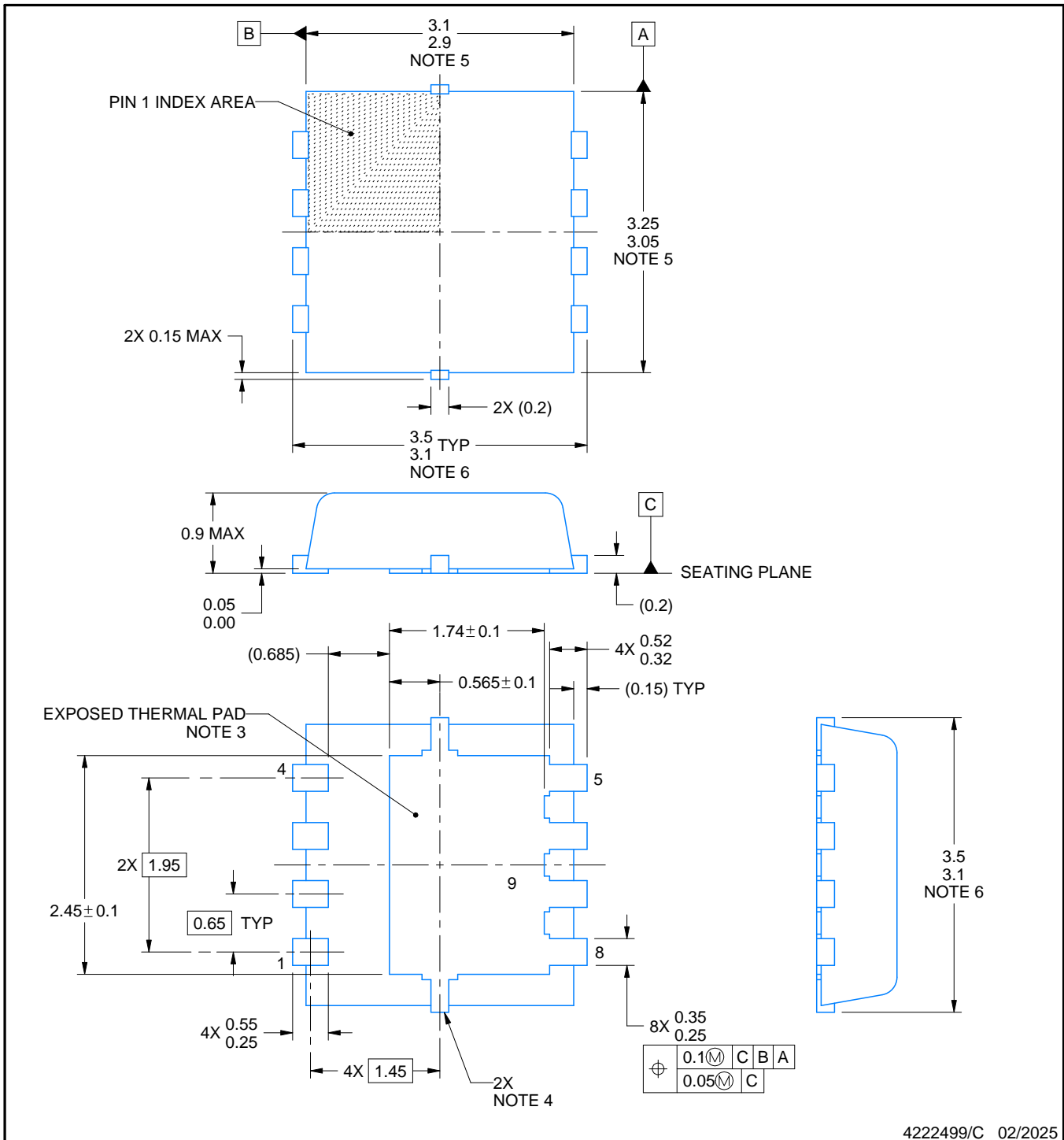
DNH0008A



PACKAGE OUTLINE

VSONP - 0.9 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



NOTES:

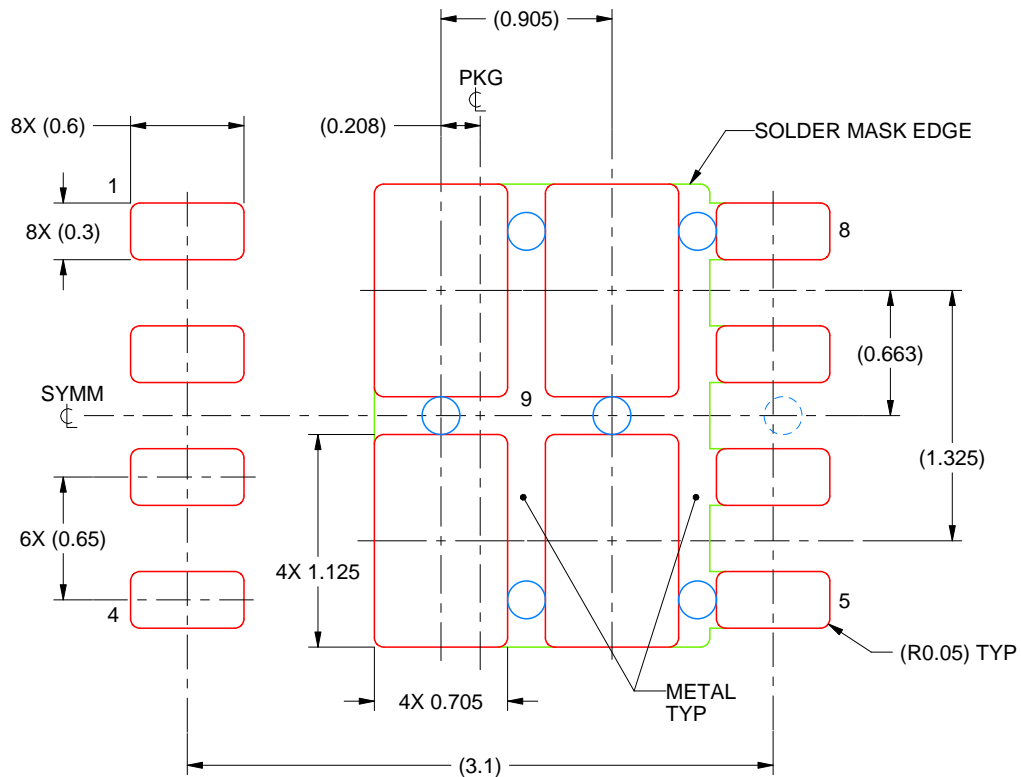
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
- Metalized features are supplier options and may not be on the package.
- These dimensions do not include mold flash protrusions or gate burrs.
- These dimensions include interterminal flash or protrusion. Interterminal flash or protrusion shall not exceed 0.25 mm per side.

EXAMPLE STENCIL DESIGN

DNH0008A

VSONP - 0.9 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 9:
76% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE: 25X

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NOTES: (continued)

9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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